

Application

LGA 2011 (Socket R Square) M4

Test result:

130W	
Flow (CFM)	Rca (°C/W)
10	0.3428
15	0.2779
20	0.2434
25	0.2233
30	0.2103
35	0.2021
40	0.194
45	0.1922
50	0.1864

Safety



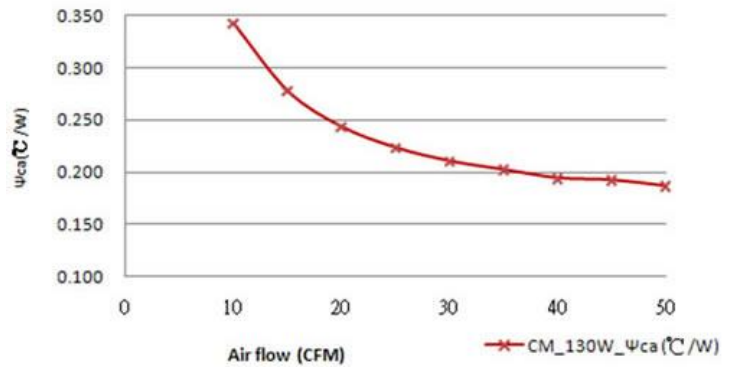
Thermal and Mechanical Spec

Thermal performance for 130W CPU

HSK Assembly Weight: 528 g

CPU Loading: 65 lbf

Performance Curve



Component Specifications

Application System 2U Form Factor Passive Solution

Material Aluminum Fin + Copper Base + Heat pipe
Diameter 6 × 2

Dimension 88.9L × 88.9W × 63H mm

Fin Thick=0.4mm, Pitch=1.55mm, 57 fin

Thermal interface Material Shin Etsu 7783 (34 × 34 mm)

*All readings are typical values at rated voltage.

*Specifications are subjected to change without notice.